Claims:

1. A tacky polymer film device for cleaning the surface of a cleaning wafer that is used to clean a probe card and a FEOL tool wafer stage, end-effector, or wafer chuck, wherein the surface tack and adhesion forces between the cleaning film and the cleaning wafer causes the debris to release from the probe card cleaning wafer and a FEOL tool cleaning wafer onto the tacky film without using a solvent, the particle removal film comprising:

a tacky cleaning pad layer;

one or more intermediate layers supporting the film and having a set of predetermined characteristics, wherein a modulus of elasticity has a range between more than 40-MPa to 600-MPa, each layer has a thickness between 25-um and 300-um and each layer has a hardness between 30 Shore A and 90 Shore A.

2. The cleaning material of claim 1, wherein the one or more intermediate layers further comprises one or more compliant layers.

3. The cleaning material of claim 1 further comprising a sacrificial top protective layer to protect and isolate the cleaning pad layer from contamination.

4. The cleaning material of claim 1 further comprising a removable release liner that is removed to expose the cleaning film surface layer.

~~5. A method for cleaning a cleaning wafer that is used to clean one of a probe card cleaning wafer and a FEOL tool cleaning wafer, the method comprising:~~

~~securing a cleaning wafer; and~~

~~applying a cleaning film to the cleaning wafer to remove debris for the cleaning wafer; and~~

~~wherein a difference in one of surface tack and adhesion force between the cleaning film and the cleaning wafer causes the debris to release from the cleaning wafer onto the cleaning film without using a solvent.~~

~~6. The method of claim 5, wherein securing the cleaning wafer further comprises placing the cleaning wafer on a vacuum chuck.~~

~~7. The method of claim 5, wherein applying the cleaning film further comprises removing a protective liner that covers a cleaning polymer layer of the cleaning film before applying the cleaning film to the cleaning wafer.~~

~~8. The method of claim 5, wherein applying the cleaning film further comprises using a manual roller to apply the cleaning film to the cleaning wafer.~~

9. The method of claim 5 further comprising discarding the cleaning film with the embedded debris.

10. The method of claim 9 further comprising returning the cleaning wafer to service after it has been cleaned using the cleaning film.

11. The method of claim 9, wherein returning to cleaning wafer to service further comprising installing the cleaning wafer back into a front end of the line piece of equipment.

12. The method of claim 9, wherein returning to cleaning wafer to service further comprising installing the cleaning wafer back into a probe card machine.

13. A method for operating a semiconductor processing piece of equipment while cleaning the semiconductor processing piece of equipment using a cleaning film, comprising:

cleaning a semiconductor processing piece of equipment using a cleaning wafer;

removing the cleaning wafer from the semiconductor processing piece of equipment;

applying a cleaning film to the cleaning wafer to remove debris for the cleaning wafer, wherein a difference in one of surface tack and adhesion force between the cleaning film and the cleaning wafer causes the debris to release from the cleaning wafer onto the cleaning film without using a solvent; and

returning to the cleaning wafer to the semiconductor processing piece of equipment so that the semiconductor processing piece of equipment is cleaned using the cleaning wafer.

14. The method of claim 13, wherein removing the cleaning wafer further comprises placing the cleaning wafer on a vacuum chuck.

15. The method of claim 13, wherein applying the cleaning film further comprises removing a protective liner that covers a cleaning polymer layer of the cleaning film before applying the cleaning film to the cleaning wafer.

16. The method of claim 13, wherein applying the cleaning film further comprises using a manual roller to apply the cleaning film to the cleaning wafer.

17. The method of claim 13 further comprising discarding the cleaning film with the embedded debris.

18. The method of claim 17 further comprising returning the cleaning wafer to service after it has been cleaned using the cleaning film.

19. The method of claim 17, wherein returning to cleaning wafer to service further comprising installing the cleaning wafer back into a front end of the line piece of equipment.

20. The method of claim 17, wherein returning to cleaning wafer to service further comprising installing the cleaning wafer back into a probe card machine.